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(54) **Title**: SEMICONDUCTOR PACKAGE WITH EMBEDDED DIE AND ITS METHODS OF FABRICATION

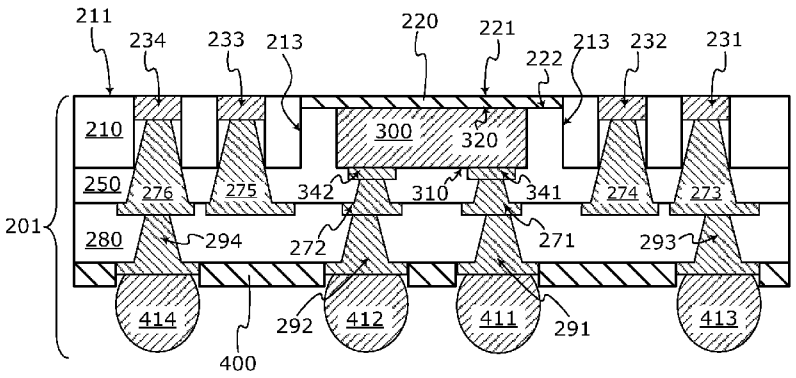


FIGURE 1

(57) **Abstract**: Embodiments of the present invention describe a semiconductor package having an embedded die. The semiconductor package comprises a coreless substrate that contains the embedded die. The semiconductor package provides die stacking or package stacking capabilities. Furthermore, embodiments of the present invention describe a method of fabricating the semiconductor package that minimizes assembly costs.

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